

AN 105:180503 HCA
TI Manufacture of high-purity electrolytic copper
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SO Jpn. Kokai Tokkyo Koho, 3 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 61084389	A2	19860428	JP 1984-204346	19840928
AB	A high-purity Cu sulfate bath contg. 90-220 g/L free SO42- is electrolyzed, using an electrolytic Cu anode, at a cathode c.d. of .ltoreq.2.5 A/dm2 and .ltoreq.40.degree. to give an electrolytic cathode Cu of purity .gtoreq.99 .999 wt.%. The refined Cu has excellent elongation properties and is useful as bonding for semiconductor devices, wires for motors, etc. Thus, a bath contg. Cu 42 and SO42- 93 g/L was electrolyzed at 25.degree. and at a cathode c.d. of 1.5 A/dm2, using a Ti cathode and an electrolytic Cu anode (purity 99.99 wt.%) which was placed in a Tetron 501 B box to deposit high-purity Cu contg. S <1, Ag <1, Fe <0.6, and Si <1 ppm on the cathode.				